PCN Number:	20180611001	1 PCN Date:			June 15, 2018			
Title: Datasheet for	or TPSM84209							
<b>Customer Contact:</b>	PCN Manager			De	pt:	Quality Services		
Change Type:								
Assembly Site		Design			Wafer	Bump Site		
Assembly Process		Data Sheet				Bump Material		
		Part number change				Bump Process		
Mechanical Specif		Test Site				Fab Site		
Packing/Shipping,	/Labeling	Test Process				Fab Materials		
					Wafer	Fab Process		
Notification Details								
Description of Change:								
Texas Instruments Incorporated is announcing an information only notification.								
The product datasheet(s) is being updated as summarized below.								
The following change history provides further details.								
TEXAS						TPSM84209		
INSTRUMENTS			SLVSE31	1B-J	ANUARY 201			
SLVSE31B – JANUARY 2018 – REVISED JUNE 2018								
Changes from Revision A (April 2018) to Revision B Page								
Changed Min Storage temperature to -55°C								
The datasheet number will be changing.								
Device Family		Change From:	ae From:		Change To:			
	SLVSE31A	<b>.</b>			SLVSE31B			
TPSM84209		JLVJLJIA	SLVSESIA S			3LV3L31D		
These changes may be reviewed at the datasheet links provided.								
http://www.ti.com/product/TPSM84209								
Reason for Change:								
To accurately reflect device characteristics.								
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):								
No anticipated impact. This is a specification change announcement only. There are no changes								
to the actual device.								
Changes to product identification resulting from this PCN:								
None.								
Product Affected:								
TPSM84209RKHT								
For questions regarding this notice, e-mails can be sent to the regional contacts shown below								
or your local Field Sales Representative.								

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com